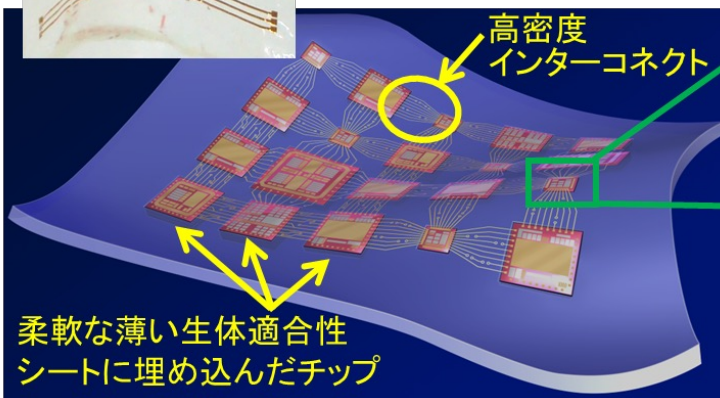
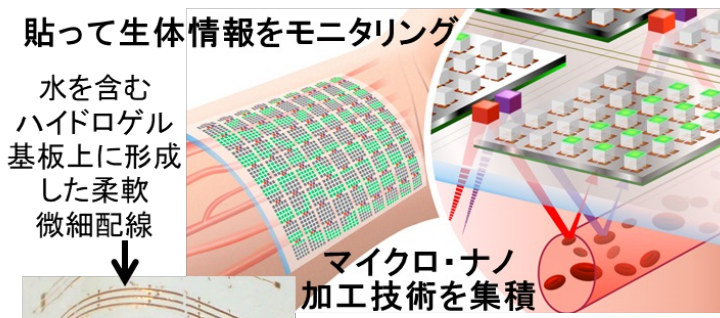
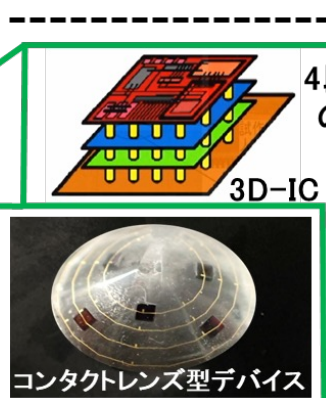
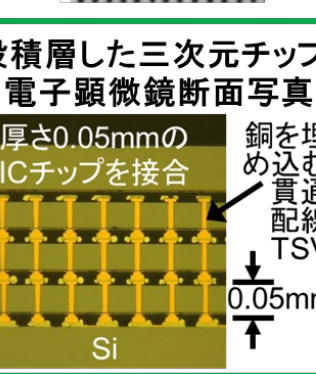
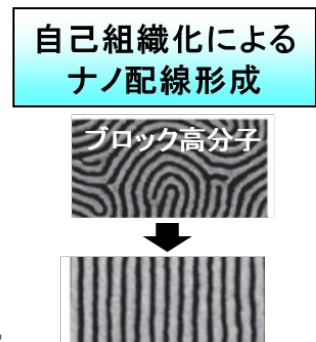




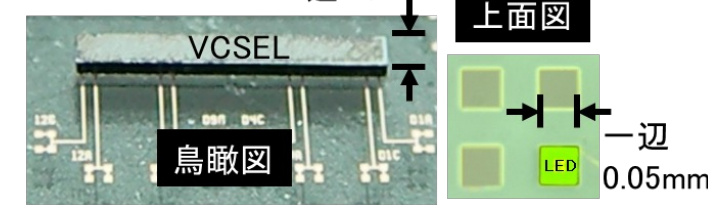
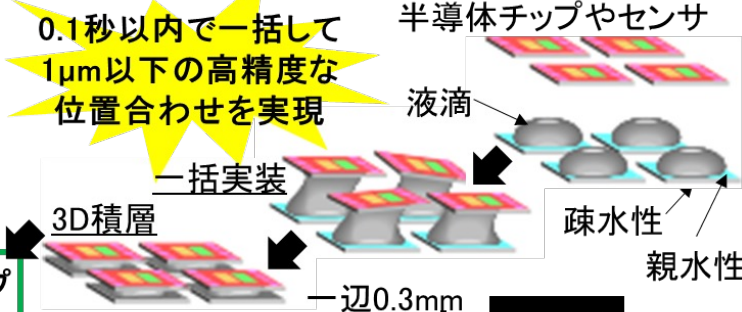
高集積なフレキシブルセンサや
ウェアラブル医療システム技術



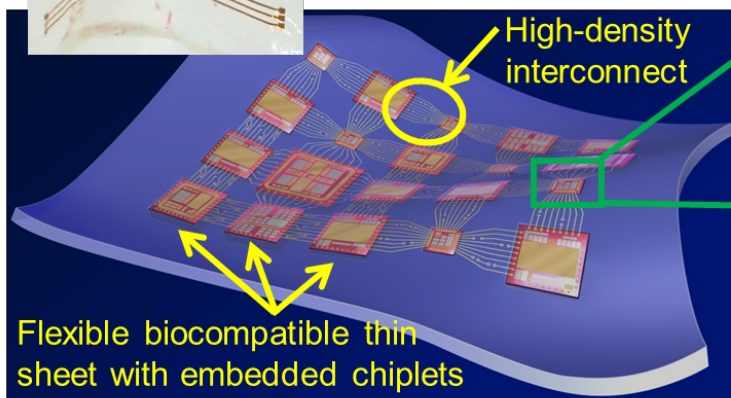
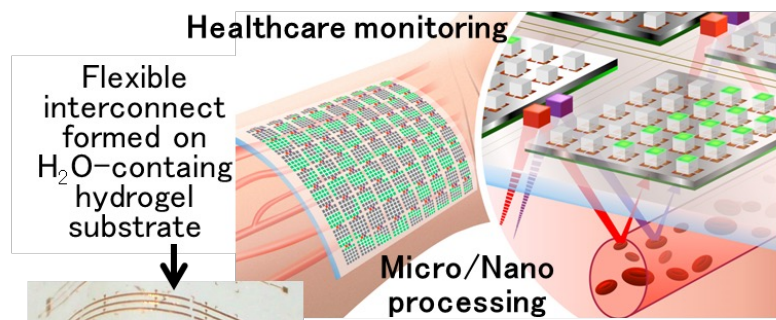
次世代人工知能を牽引する
脳の構造を模したAI半導体技術



”半導体”研究に興味がある方はお気軽に
お問合せ下さい。fukushima-tak@tohoku.ac.jp

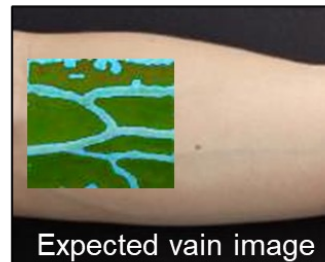


自己組織化実装により接合した
面発光レーザーVCSEL(左)と極小LED(右)
ロボットでは掴めない極小構造体の
高精度集積技術“セルフアセンブリ”

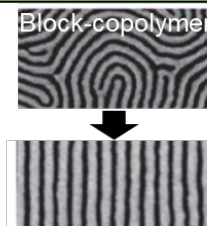


Flexible hybrid sensor system integration technology

Smart Skin Display

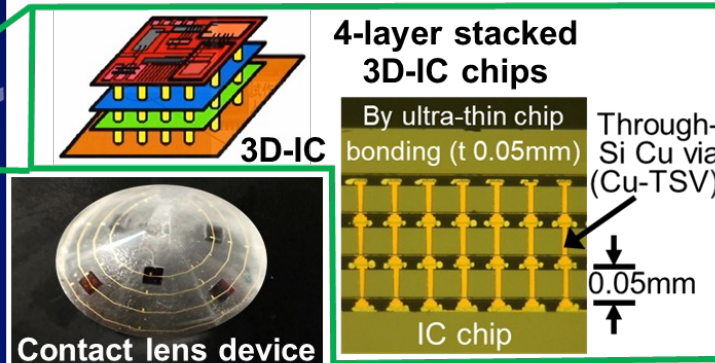
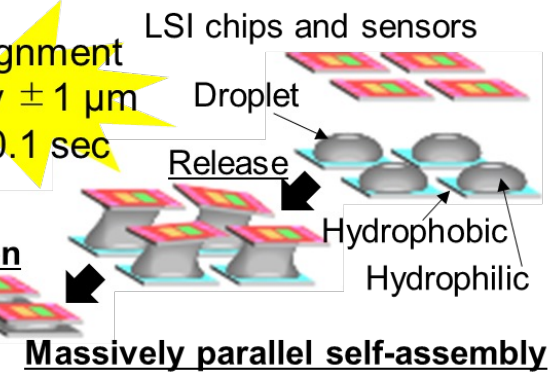


Directed self-assembly (DSA) for ultra-fine wire

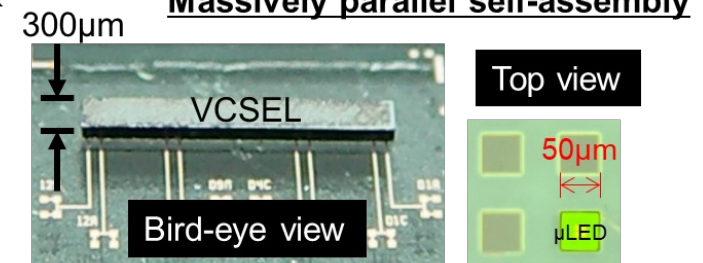


High alignment accuracy $\pm 1 \mu\text{m}$ within 0.1 sec

3D integration



Three-dimensional brain-like chip fabrication technology



Self-assembled VCSEL (left) and tiny micro-LED (right)

Ultra-small chiplet self-assembly technology